









# PRODUCT DATASHEET



- ► Subminiature SMD
- ► 2421 Series
- ► Blue (465nm)

NOB11S98RV











Package: Subminiature SMD Forward Current: 20mA Forward Voltage (typ.): 3.1V

Luminous Intensity (typ.): 50mcd @20mA

Colour: Blue

Wavelength: 465nm Viewing angle: 150°

**Materials:** 

Die: InGaN

Resin: Epoxy (Water Clear) Operating Temperature: -40~+80°C

Storage Temperature: -40~+85°C

**Grouping parameters:** 

Forward voltage

Luminous intensity

Dominant wavelength

Soldering methods: Reflow

Preconditioning: acc. to JEDEC Level 3

Packing: 12mm tape with 2000/reel, ø180mm (7")

### **APPLICATIONS:**

Subminiature 2421

- Backlighting
- Indication Light
- Switch light
- Dashboard



### **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

| Parameter                          | Symbol           | Ratings | Unit |
|------------------------------------|------------------|---------|------|
| Forward Current                    | I <sub>F</sub>   | 30      | mA   |
| Peak Forward Current Duty 1/8@1KHz | I <sub>FP</sub>  | 125     | mA   |
| Reverse Current @5V                | I <sub>R</sub>   | 10      | μΑ   |
| Power Dissipation                  | P <sub>D</sub>   | 111     | mW   |
| Operating Temperature              | T <sub>OPR</sub> | -40~+80 | °C   |
| Storage Temperature                | T <sub>STG</sub> | -40~+85 | °C   |

# Electrical & Optical Characteristics (Ta=25°C)

| Parameter                       | Cumbal                           | Values |      |      | Unit | Test                 |
|---------------------------------|----------------------------------|--------|------|------|------|----------------------|
| Parameter                       | Symbol                           | Min.   | Тур. | Max. | Onit | Condition            |
| Forward Voltage                 | $V_{F}$                          | 2.8    | 3.1  | 3.7  | V    | I <sub>F</sub> =20mA |
| Luminous Intensity              | I <sub>V</sub>                   | 20     | 50   | 100  | mcd  | I <sub>F</sub> =20mA |
| Dominant Wavelength             | $\lambda_{\scriptscriptstyle D}$ | 460    | 465  | 470  | nm   | I <sub>F</sub> =20mA |
| Peak Wavelength                 | $\lambda_{	extsf{P}}$            |        | 460  |      | nm   | I <sub>F</sub> =20mA |
| Spectral Line Half<br>Bandwidth | Δλ                               |        | 26   |      | nm   | I <sub>F</sub> =20mA |
| Viewing Angle                   | 2θ <sub>1/2</sub>                |        | 150  |      | deg  | I <sub>F</sub> =20mA |

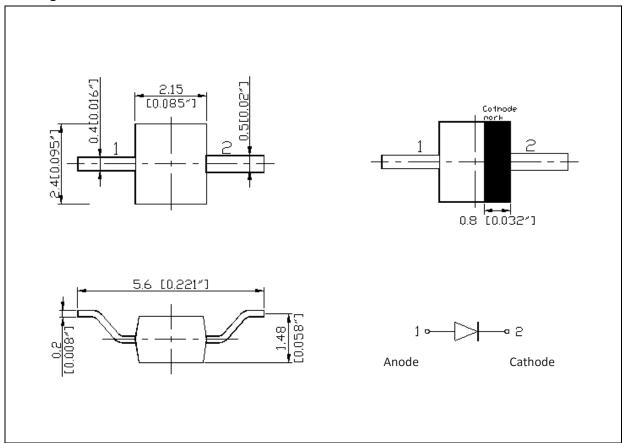
<sup>1.</sup> Luminous intensity (I<sub>V</sub>) ±15%, Forward Voltage (V<sub>F</sub>) ±0.1V, Viewing angle(2 $\theta_{1/2}$ ) ±5%

<sup>2.</sup> IS standard testing



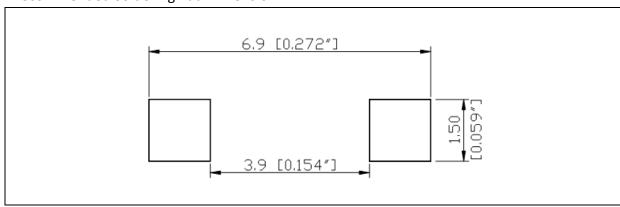
### **OUTLINE DIMENSION:**

### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

# **Recommended Soldering Pad Dimension:**



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5$ °.



# **BINNING GROUPS:**

# Forward Voltage Classifications (I<sub>F</sub> = 20mA):

| Code | Min. | Max. | Unit |
|------|------|------|------|
| F    | 2.8  | 3.1  |      |
| G    | 3.1  | 3.4  | V    |
| Н    | 3.4  | 3.7  |      |

# Luminous Intensity Classifications ( $I_F = 20mA$ ):

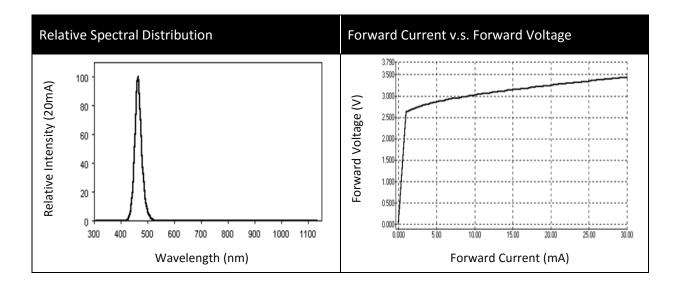
| Code | Min. | Max. | Unit |
|------|------|------|------|
| E    | 20   | 30   |      |
| F    | 30   | 40   |      |
| G    | 40   | 50   | mad  |
| Н    | 50   | 63   | mcd  |
| I    | 63   | 80   |      |
| J    | 80   | 100  |      |

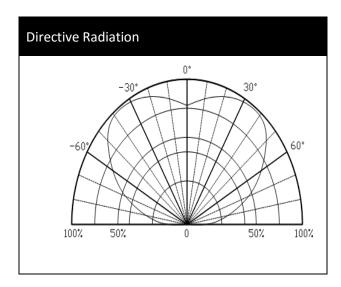
# Dominant Wavelength Classifications ( $I_F = 20$ mA):

| Code | Min. | Max. | Unit |
|------|------|------|------|
| M    | 460  | 465  |      |
| N    | 465  | 470  | nm   |



### **ELECTRO-OPTICAL CHARACTERISTICS:**

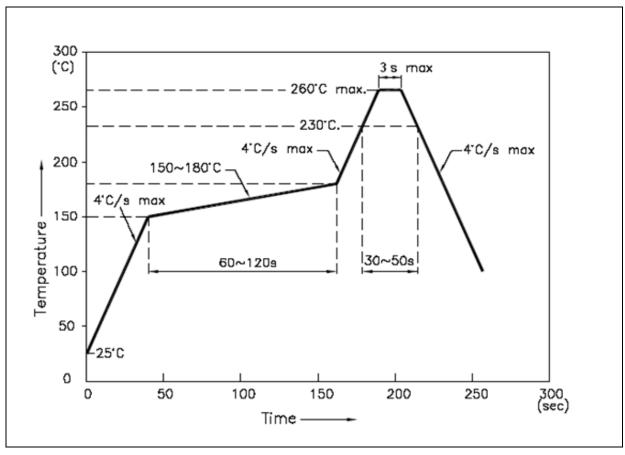






### **RECOMMENDED SOLDERING PROFILE:**

# Reflow Solder:



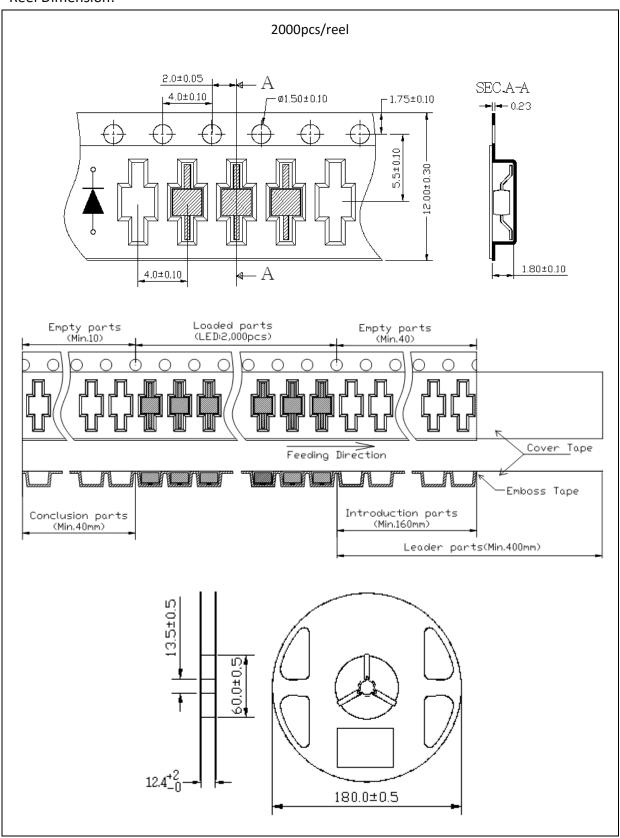
### Note:

- 1. Recommend reflow temperature 245°C.
- 2. Maximum reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



### **PACKING SPECIFICATION:**

#### Reel Dimension:





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

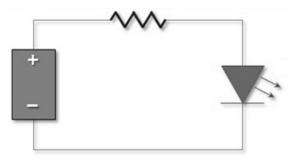
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.</li>
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

|   | Version | Date       | Summary of Revision                             |
|---|---------|------------|---|
|   | A1.0    | 07/08/2014 | Datasheet set-up.                               |
| ĺ | A1.1    | 15/09/2016 | Part number adds -RV to indicate reverse mount. |